



Material Content Data Sheet



Sales Product Name		ICE3A2065ELJ		Issued		22. January 2018		
MA#		MA000981076						
Package		PG-DIP-8-13		Weight*		557.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.346	0.78	0.78	7798	7798
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7709	
wire	non noble metal	copper	7440-50-8	174.475	31.30	32.12	313012	321202
	noble metal	gold	7440-57-5	0.282	0.05	0.05	506	506
	encapsulation	organic material	carbon black	1333-86-4	1.091	0.20		1956
encapsulation	plastics	epoxy resin	-	35.261	6.33		63259	
	inorganic material	silicondioxide	60676-86-0	327.162	58.70	65.23	586937	652152
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13448	13448
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1428	1428
glue	plastics	epoxy resin	-	0.290	0.05		520	
	noble metal	silver	7440-22-4	1.642	0.29	0.34	2946	3466
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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